

623-0248-H26 General Specifications

■ Mechanical

- Typical Application: BGA
- Minimum Device Pitch: 0.40 mm
- Force: 35.0 gf @ 0.6 mm Recommended Travel
- Operating Temperature Range: -55°C to 120°C
- Device Side Contact: 4-point Crown Tip
- PCB Side Contact: Conical Radius Tip

■ Electrical

- Bandwidth @ -1 dB: up to 10 GHz
 - Based on G-S-G Pattern
- Contact Resistance: < 60 mΩ average
- Current Carrying Capability: 3.0 A
 - Measured in free air

■ Plating

- Device Side Plunger: Homogenous alloy
- PCB Side Plunger: Gold plated
- Barrel: Gold plated
- Spring: Gold plated

